

MATERIAL DECLARATION SHEET



Material Number	AD##ABB			
Product Line	Thermal Cut-Off			
Compliance Date	6 December, 2022			
RoHS Compliant	Y	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	AD##ABB	Cover and Base Resin	0.030	Poly(thio-1,4-phenylene) <Polyphenylene Sulfide>	25212-74-2	65-75%	25.4%	
				Potassium octatitanate	59766-31-3	25-35%		
				Copper	7440-50-8	0-1%		
2		Cover Plate	0.038	Carbon	7440-44-0	0.15% Max.	32.6%	
				Silicon	7440-21-3	1.00% Max.		
				Manganese	7439-96-5	2.00% Max.		
				Phosphorus	7723-14-0	0.045% Max.		
				Sulfur	7704-34-9	0.030% Max.		
				Nickel	7440-02-0	6.00%-8.00%		
				Chromium	7440-47-3	16.00%-18.00%		
3	Bimetal Disc	0.005	Iron	7439-89-6	Remain	4.3%		
			Nickel	7440-02-0	27.0%			
			Cobalt	7440-48-4	4.2%			
			Chromium	7440-47-3	1.4%			
			Manganese	7439-96-5	0.3%			
			Iron	7439-89-6	67.1%			

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4	AD##ABB	Arm	0.017	Copper	7440-50-8	Remain	14.2%	
				Chromium	7440-47-3	0.24%		
Magnesium				7439-95-4	0.10%			
Silver				7440-22-4	3.66%			
Nickel				7440-02-0	0.40%			
Tin				7440-31-5	0.14%			
5		Base Terminal	0.023	Copper	7440-50-8	Remain	19.5%	
				Chromium	7440-47-3	0.23%		
				Magnesium	7439-95-4	0.09%		
				Silver	7440-22-4	6.10%		
				Nickel	7440-02-0	0.62%		
	Tin			7440-31-5	0.11%			
6	PTC	0.005	PTC Ceramic body	12047-27-7	Remain	4.0%		
			*Lead	7439-92-1	1-6%			
		Total weight	0.118					

This Document was updated on:

Important remarks:

- It is the responsibility of the user to verify they are accessing the latest version.
- * PTC contains Lead or its compounds. It is exempted by EU RoHS directive 2011/65/EU based on ANNEX III 7(c)-I as follows;
 "Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound."